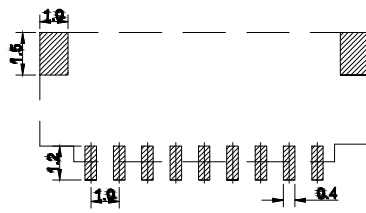
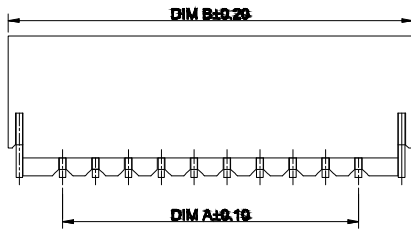
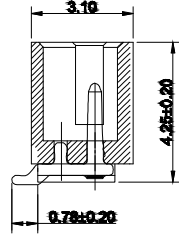
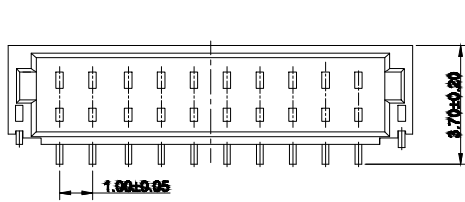




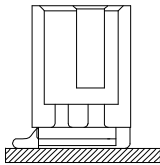
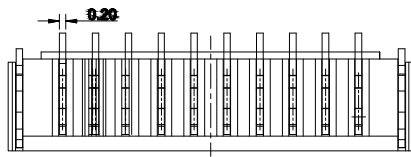
SPECIFICATION

Current Rating:1.0Amp
 Contact Resistance:20mΩ Max
 Withstand Voltage:500V AV/Minute
 Insulation Resistance:100MΩ Min
 Operation Temperature:-25℃ to +85℃

Contact Material Brass
 Contact Plating:Au or Sn over Ni
 Insulator Material:PA9T UL94V-0



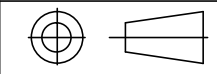
P.C.B Layout



Assembly Layout

Circuit	Dimension	
	A	B
2	1.00	4.50
3	2.00	5.50
4	3.00	6.50
5	4.00	7.50
6	5.00	8.50
7	6.00	9.50
8	7.00	10.50
9	8.00	11.50
10	9.00	12.50
11	10.00	13.50
12	11.00	14.50
13	12.00	15.50
14	13.00	16.50
15	14.00	17.50
16	15.00	18.50
17	16.00	19.50
18	17.00	20.50
19	18.00	21.50
20	19.00	22.50

Any size and shape can be customized.
 Contact sales team for more information.



PRODUCT NAME	DIM	TOL	DWG NO.	DRAW	Wu	PART NO	CUST
1.0 MM Wire to Board SMT Wafer	X. X	±0.3	P. W	CHECK	Tomy	UNIT	DATE
	X. XX	±0.2	MATER	APPR	Allan	MM[INCH]	XXXX. XX. XX
	ANGLE	±3°	REV.				
			BRASS PA9T			东莞市同盈电子有限公司 DONGGUAN WIN-WIN ELECTRONIC Co., Ltd.	
			A0				